

1MHz, 3A Synchronous Step-Down Regulator

Features

- High Efficiency: Up to 95%
- Low Quiescent Current: Only 50µA During Operation
- Internal Soft Start Function
- Output Current
G5719CTB1U: 2A Continuous, 3A Peak
G5719CRC1U: 3A Continuous
- 2.5V to 6V Input Voltage Range
- 1MHz Switching Frequency
- No Schottky Diode Required
- 100% Duty Cycle in Dropout Operation
- 0.6V Reference Allows Low Output Voltages
- <1µA Shutdown Current
- Current Mode Operation for Excellent Line and Load Transient Response
- Over Temperature Protected
- RoHS Compliant
- Power Good
- Output Short Circuit Latch-off Protection
- Output Overvoltage Latch-off Protection

General Description

The G5719C is a high efficiency monolithic synchronous buck regulator using a constant frequency, current mode architecture. Supply current during operation is only 50µA and drops to <1µA in shutdown. The 2.5V to 6V input voltage range makes the G5719C ideally suited for single Li-Ion battery-powered applications. 100% duty cycle provides low dropout operation, extending battery run time in portable systems. Switching frequency is internally set at 1MHz, allowing the use of small surface mount inductors and capacitors. The internal synchronous switch increase efficiency and eliminates the need for an external Schottky diode. Built-in soft start function eliminates in-rush current that could damage the system. Output latch-off operation protects the step-down regulator from damage under short circuit and overvoltage conditions.

Applications

- Cellular Telephones
- Personal Information Appliances
- Microprocessors and DSP Core Supplies
- Wireless and DSL Modems
- Digital Still and Video Cameras
- MP3 Players
- Portable Instruments

Ordering Information

ORDER NUMBER	MARKING	OUTPUT VOLTAGE	TEMP. RANGE	PACKAGE (Green)
G5719CTB1U	519Cx	Adjustable	-40°C to +85°C	SOT-23-6
G5719CRC1U	519C	Adjustable	-40°C to +85°C	TDFN2X2-8

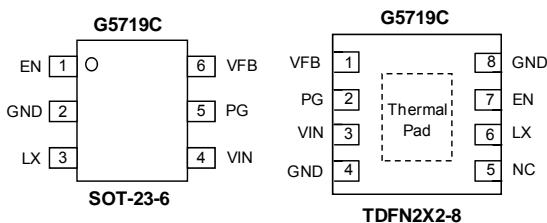
Note: TB: SOT-23-6 RC: TDFN2X2-8

1: Bonding Code

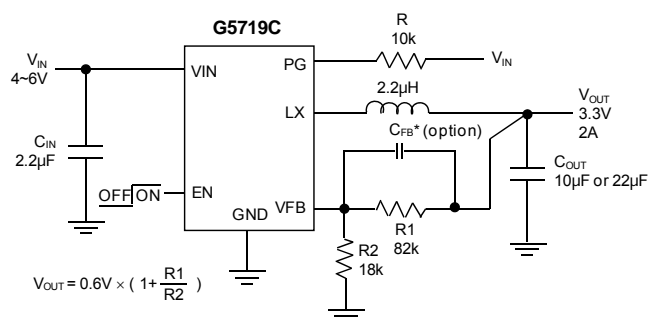
U: Tape & Reel

Green : Lead Free / Halogen Free.

Pin Configuration



Typical Application Circuit



Absolute Maximum Ratings

VIN to GND	-0.3V to +7V	Thermal Resistance Junction to Case, (θ_{JC})	
EN, VFB to GND	-0.3V to (VIN + 0.3V)	SOT-23-6	60°C/W
LX to GND	-0.3V to (VIN + 0.3V)	TDFN2X2-8	63°C/W
LX to GND	-3V to (VIN + 3V) for <20ns	Operating Temperature Range	-40°C to 85°C
Thermal Resistance Junction to Ambient, (θ_{JA})		Maximum Junction Temperature	150°C
SOT-23-6	240°C/W ⁽¹⁾	Storage Temperature Range	-65°C to 165°C
TDFN2X2-8 (1in ²)	127°C/W ⁽²⁾	Reflow Temperature (soldeing, 10 sec)	260°C
Continuous Power Dissipation (TA = +25°C)			
SOT-23-6	0.52W ⁽¹⁾		
TDFN2X2-8 (1in ²)	1.0W ⁽²⁾		

Note:

⁽¹⁾: Please refer to Minimum Footprint PCB Layout Section.

⁽²⁾: Please refer to 1in² of 1oz PCB Layout Section.

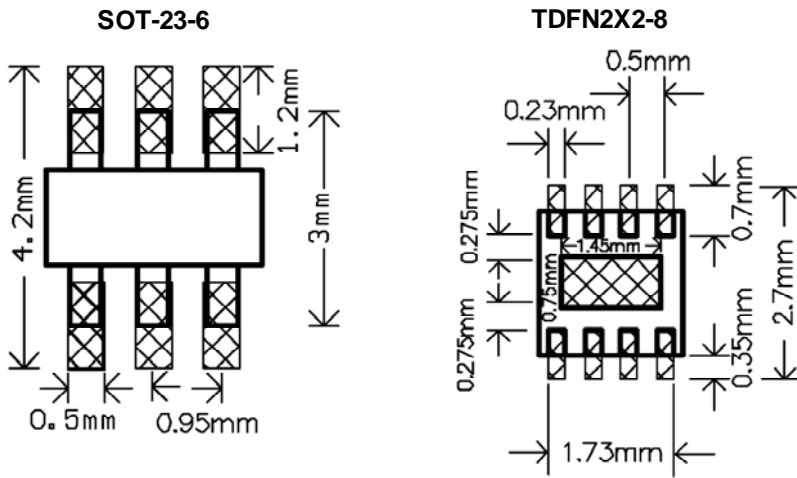
Electrical Characteristics

TA=25°C, VIN=3.6V.

The device is not guaranteed to function outside its operating conditions. Parameters with MIN and/or MAX limits are 100% tested at +25°C, unless otherwise specified.

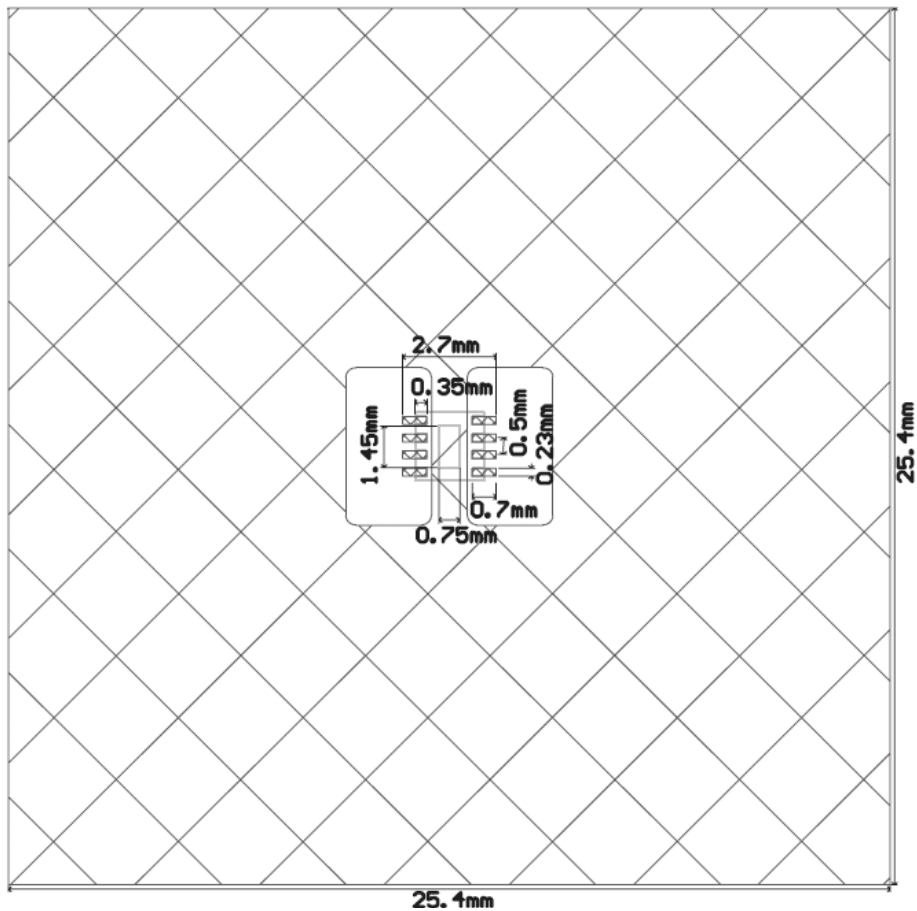
PARAMETER	CONDITION	MIN	TYP	MAX	UNIT
Feedback Current		-30	0	+30	nA
Regulated Feedback Voltage		0.588	0.6	0.612	V
Reference Voltage Line Regulation	VIN = 2.5V to 5.5V	-0.1	---	0.1	%/V
Peak Inductor Current	VIN = 5V	3.2	---	5	A
Output Voltage Load Regulation	0.2A ≤ IO ≤ 3A	---	0.5	---	%/A
Input Voltage Range		2.5	---	6	V
Quiescent Current	Active Mode (no switching)	30	50	150	μA
	Shutdown Mode	---	0	1	
Oscillator Frequency		0.8	1.0	1.2	MHz
RDS(ON) of P-Channel FET	ILX = 2A	70	100	150	mΩ
RDS(ON) of N-Channel FET	ILX = 2A	70	80	120	mΩ
EN Threshold	Logic High	1	---	---	V
	Logic Low	---	---	0.4	
EN Leakage Current		---	0	1	μA
Input UVLO Threshold	VUVLO	---	2	---	V
UVLO Hysteresis		---	0.2	---	V
Maximum Duty Cycle		100	---	---	%
Minimum On Time		---	75	---	ns
Output Latch-off Threshold	VFB (Overvoltage)	0.66	0.72	0.795	V
	VFB (Short Circuit)	0.5	0.54	0.55	
Thermal Shutdown Threshold	Hysteresis = 30°C	---	147	---	°C
LX Discharge Resistance	RDIS	---	55	---	Ω
Soft Start Time	TSS	0.7	1.5	2	ms

Minimum Footprint PCB Layout Section



1in² of 1oz PCB Layout Section

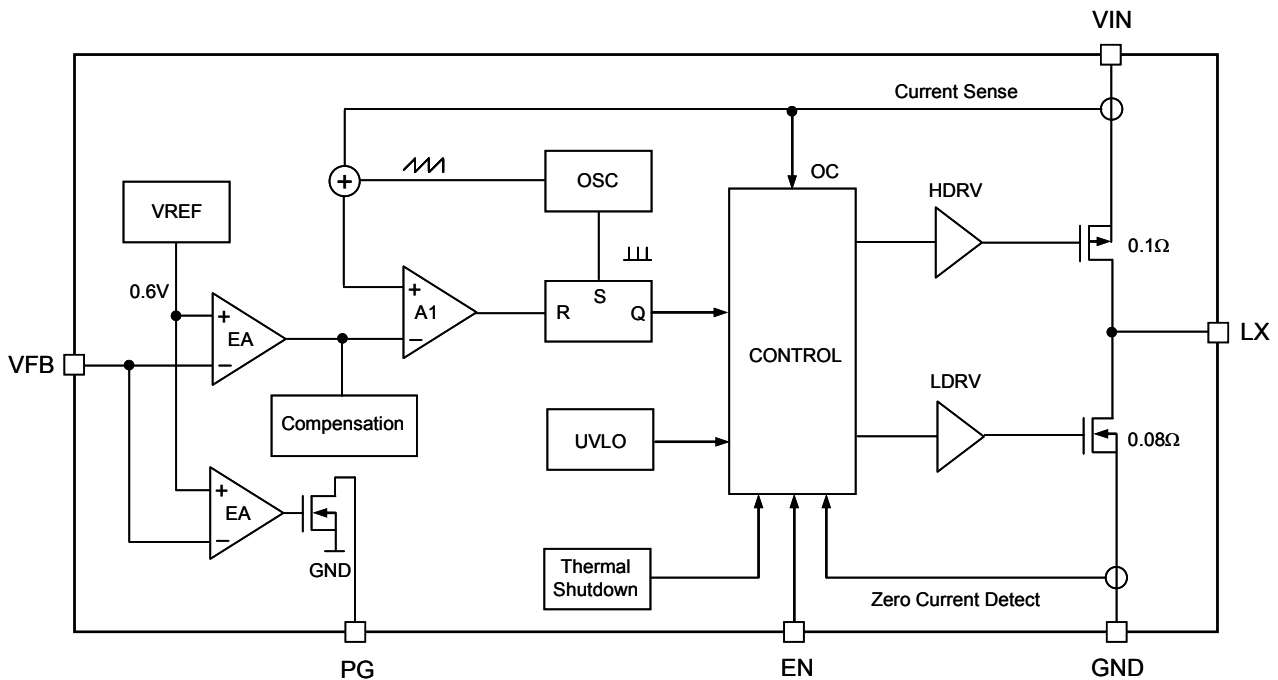
TDFN2X2-8



Pin Descriptions

PIN		NAME	FUNCTION
SOT-23-6	TDFN2X2-8		
1	7	EN	Enable Control Pin (Active high, do not leave EN pin floating)
2	4,8	GND	Ground Pin
3	6	LX	Switch Pin
4	3	VIN	Input Supply Pin
6	1	VFB	Feedback Pin
5	2	PG	Power Good. When V_{OUT} is within 10% of regulation point, the output is open drain.
---	5	NC	No Connection

Block Diagram



Function Description

Normal Operation

The G5719C uses a constant frequency, current mode step-down architecture. Both the high/low-side switches are internal. During normal operation, the internal high-side (PMOS) switch is turned on each cycle when the oscillator sets the SR latch, and turned off when the comparator (A1) resets the SR latch. The peak inductor current at which comparator (A1) resets the SR latch, is controlled by the output of error amplifier EA. While the high-side switch is off, the low-side switch is turned on until either the inductor current starts to reverse or the beginning of the next switching cycle.

Dropout Operation

As the input supply voltage decreases to a value approaching the output voltage, the duty cycle increases toward the maximum on-time. Further reduction of the supply voltage forces the high-side switch to remain on for more than one cycle until it reaches 100% duty cycle. The output voltage is dropped from the input supply for the voltage which across the high-side switch.

Over Temperature Protection

In most applications the G5719C does not dissipate much heat due to high efficiency. But, in applications where the G5719C is running at high ambient temperature with low supply voltage and high duty cycles, such as in dropout, the heat dissipated may exceed the maximum junction temperature of the part. If the junction temperature reaches approximately 150°C, both power switches will be turned off and the SW node will become high impedance.

Soft-Start

The G5719C employs soft-start circuitry to reduce supply inrush current during startup conditions. When the device exits under-voltage lockout or shut-down mode, the soft-start circuitry will slowly ramp up the output voltage.

Over Current Protection

The G5719C cycle-by-cycle limits the peak inductor current to protect embedded switch from damage. Hence the maximum output current (the average of inductor current) is also limited. In case the load increases, the inductor current is also increase. Whenever the current limit level is reached, the output voltage can not be regulated and starting to drop.

Short-circuit and Overvoltage Latch-Off Protection

Short-circuit latch-off protection will activate once the feedback voltage falls below 0.54V. Besides, Over-voltage latch-off protection will also activate once the feedback voltage rises beyond 0.72V. The function latches off the output to provide fault protection until

those conditions are removed and the step-down regulator is reset by enable control.

Application Information

Inductor Selection

For most applications, the value of the inductor will fall in the range of 2.2μH to 10μH. Its value is chosen based on the desired ripple current. Large value inductors lower ripple current and small value inductors result in higher ripple currents. Higher V_{IN} or V_{OUT} also increase the ripple current ΔI_L :

$$\Delta I_L = \frac{1}{fL} V_{OUT} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$

where f =switching frequency, L =inductance. A reasonable inductor current ripple is usually set as 1/2 to 1/5 of maximum out current.

The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation. For better efficiency, choose a low DCR inductor.

Capacitor Selection

In continuous mode, the source current of the top MOSFET is a square wave of duty cycle V_{OUT}/V_{IN} . To prevent large voltage transients, a low ESR input capacitor sized for maximum RMS current must be used. The maximum RMS capacitor current is given by:

$$C_{IN} \text{ requires } I_{RMS} \cong I_{OMAX} \frac{\sqrt{V_{OUT}(V_{IN} - V_{OUT})}}{V_{IN}}$$

This formula has a maximum at $V_{IN}=2V_{OUT}$, where $I_{RMS}=I_{OUT}/2$. This simple worst case condition is commonly used for design because even significant deviations do not offer much relief.

The selection of C_{OUT} is driven by the required effective series resistance (ESR). Typically, once the ESR requirement for C_{OUT} has been met, the RMS current rating generally far exceeds the $I_{RIPPLE(P-P)}$ requirement. The output ripple ΔV_{OUT} is determined by:

$$\Delta V_{OUT} \cong \Delta I_L \left(ESR + \frac{1}{8fC_{OUT}} \right)$$

For a fixed output voltage, the output ripple is highest at maximum input voltage since ΔI_L increases with input voltage.

Nowadays, higher value, lower cost ceramic capacitors are becoming available in smaller case sizes. Their high ripple current, high voltage rating and low ESR make them ideal for switching regulator applications. Because the G5719C's control loop does not depend on the output capacitor's ESR for stable operation, ceramic capacitors can be used freely to achieve very low output ripple and small circuit size.

When choosing the input and output ceramic capacitors, choose the X5R or X7R dielectric formulations. These dielectrics have the best temperature and voltage characteristics of all the ceramics for given value and size.

Output Voltage Programming

In the adjustable version of G5719C, the output voltage is set by a resistive divider according to the following formula:

$$V_{OUT} = 0.6 \times \left(1 + \frac{R1}{R2} \right) \text{ Volt.}$$

Parameters Suggestion Table

V _{OUT} (V)	R1(KΩ)	R2(KΩ)	L(μH)	C _{OUT} (μF)
3.3	115	25.5	3.3	22
2.5	25.5	8.06	3.3	22
1.8	20	10	2.2	22
1.2	10	10	2.2	22

Efficiency Considerations

Although all dissipative elements in the circuit produce losses, one major source usually account for most of the losses in G5719C circuits: I²R losses. The I²R loss dominates the efficiency loss at medium to high load currents.

The I²R losses are calculated from the resistances of the internal switches, R_{SW}, and external inductor R_L. In continuous mode, the average output current flowing through inductor L is "chopped" between the main switch and the synchronous switch. Thus the series resistance looking into the LX pin is a function of both top and bottom MOSFET R_{DS(ON)} and the duty cycle (D) as follows:

$$R_{SW} = (R_{DS(ON)TOP})(D) + (R_{DS(ON)BOTTOM})(1-D)$$

The R_{DS(ON)} for both the top and bottom MOSFETs can be obtained from Electrical Characteristics table. Thus, to obtain I²R losses, simply add R_{SW} to R_L and multiply the result by the square of the average output current.

Other losses including C_{IN} and C_{OUT} ESR dissipative losses and inductor core losses generally account for less than 2% total additional loss.

Checking Transient Response

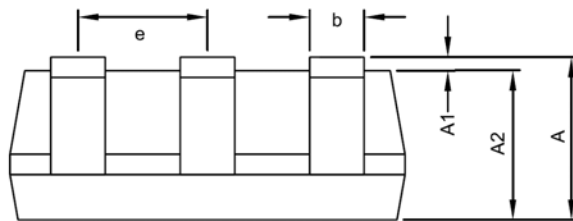
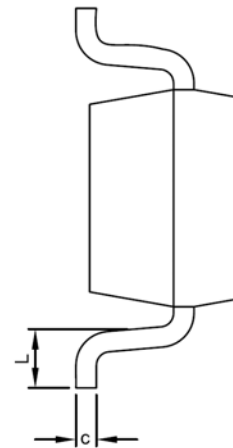
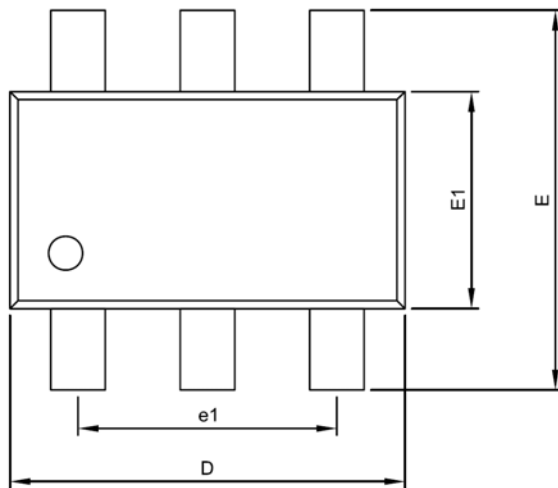
The regulator loop response can be checked by looking at the load transient response. Switching regulators take several cycles to respond to a step in load current. When a load step occurs, V_{OUT} immediately shifts by an amount equal to (ΔI_{LOAD} × ESR), where ESR is the effective series resistance of C_{OUT}. ΔI_{LOAD} also begins to charge or discharge C_{OUT}, which generates a feedback error signal. The regulator loop then acts to return V_{OUT} to its steady-state value. During this recovery time V_{OUT} can be monitored for overshoot or ringing that would indicate a stability problem.

Thermal considerations

In most application the G5719C does not dissipate much heat due to its high efficiency. But, in applications where the G5719C is running at high ambient temperature with low supply voltage and high duty cycles, such as in dropout, the heat dissipated may exceed the maximum junction temperature of the part. If the junction temperature reaches approximately 150°C, both power switches will be turned off and the LX node will become high impedance.

Assume power dissipation on G5719C P_D=0.1W, ambient temperature T_A=70°C, thermal resistance of junction to ambient R_{JA}=250°C/W, then temperature junction T_J = T_A + R_{JA} × P_D = 95°C.

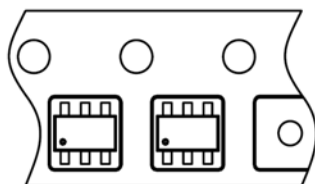
Package Information



SOT-23-6 Package

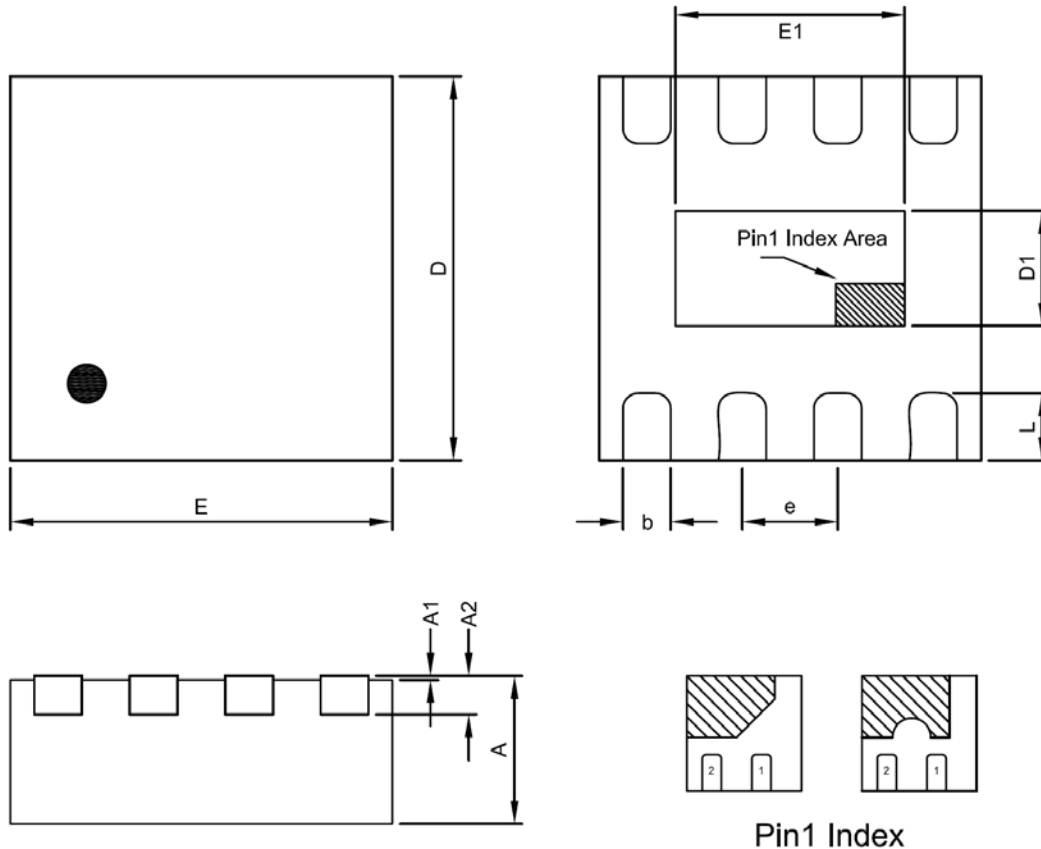
Symbol	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.95	1.10	1.45	0.037	0.043	0.057
A1	0.00	---	0.15	0.000	---	0.006
A2	0.90	1.10	1.30	0.035	0.043	0.051
D	2.70	2.90	3.10	0.106	0.114	0.122
E	2.60	2.80	3.00	0.102	0.110	0.118
E1	1.50	1.60	1.70	0.059	0.063	0.067
c	0.08	0.15	0.25	0.003	0.006	0.010
b	0.30	0.40	0.50	0.012	0.016	0.020
e	0.95 BSC			0.037 BSC		
e1	1.90 BSC			0.075 BSC		
L	0.30	0.45	0.60	0.012	0.018	0.024

Taping Specification



Feed Direction

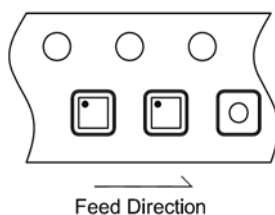
PACKAGE	Q'TY/REEL
SOT-23-6	3,000 ea



TDFN2X2-8 Package

Symbol	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.0276	0.0295	0.0315
A1	0.00	---	0.05	0.0000	---	0.0020
A2	0.20 REF			0.0079 REF		
D	1.95	2.00	2.05	0.0768	0.0787	0.0807
E	1.95	2.00	2.05	0.0768	0.0787	0.0807
D1	0.55	0.75	0.95	0.0217	0.0295	0.0374
E1	1.15	1.40	1.65	0.0453	0.0551	0.0650
b	0.15	0.23	0.30	0.0059	0.0091	0.0118
e	0.50 BSC			0.0197 BSC		
L	0.30	0.35	0.40	0.0118	0.0138	0.0157

Taping Specification



PACKAGE	Q'TY/REEL
TDFN2X2-8	3,000 ea

GMT Inc. does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and GMT Inc. reserves the right at any time without notice to change said circuitry and specifications.